A1

4) A method according to claim 1 wherein the substrate is composed of plural layers.

A2

6) A method according to claim 4 wherein each said layer comprises different materials or combinations of materials.

A3

8) A method according to claim 1 including the additional step of optically monitoring the cutting region, the cutting process being controlled in response to the said optical monitoring.

A4

12) Apparatus according to claim 1 wherein the substrate is composed of plural layers.

A5

14) Apparatus according to claim 9 wherein at least two of the said laser beams provide laser light having different parameters.

A6

16) Apparatus according to claim 12 wherein each said layer comprises different materials or combinations of materials.

A7

18) Apparatus according to claim 9 wherein beam splitter means are provided so that at least two laser beams are derived from the same laser source.

A1, cont

19) Apparatus according to claim 9 wherein optical monitoring means are provided for optically monitoring the cutting region, means being provided to control the cutting process in response to the said optical monitoring